NC259 SAC305 T6/T7 NO CLEAN SOLDER PASTE

FEATURES

- Formulated with SAC305
- 8-hour Print Life
- Nitrogen Reflow Required
- <0.66AR Print Capable
- High Tack
- Type 6 or 7 Alloy Powder

DESCRIPTION

AIM's NC259 solder paste has been developed for use with various alloys including SAC305. NC259 provides long print life and consistent print definition. The NC259 activator system promotes wetting and paste coalescence. When combined with SAC305, NC259 produces bright, smooth solder joints with high shear strength and minimal voiding.

HANDLING & STORAGE

PARAMETER	TIME	TEMPERATURE
Refrigerated Shelf Life	3 months	0°C-12°C (32°F-55°F)
Unrefrigerated Sealed Shelf Life	48 Hours	< 25°C (< 77°F)

NC259 SAC305 T6/T7 should be consumed within 24 hours after packaging seal is broken. Paste may remain on the printer for 6-8 hours. Never add used paste to unused paste. Store used paste separately; keep unused paste tightly sealed with internal plug or end cap in place. Please refer to NC259 Certificate of Analysis for product specific information.

Additional handling recommendations can be found at https://aimsolder.com/sites/default/files/aim_paste_handling_guideline_revnf1.pdf

CLEANING

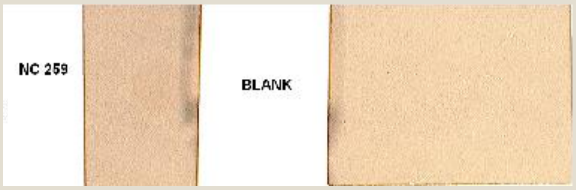
Pre-Reflow: AIM stencil cleaner effectively removes NC259 solder paste from stencils while in process. Stencil cleaner can be hand applied or used in under stencil wipe equipment. Stencil cleaner will not dry NC259 and will enhance transfer properties. Do not over-apply stencil cleaner. Do not apply stencil cleaner to stencil topside. Isopropanol (IPA) is not recommended in process but may be used as a final stencil rinse.

Post-Reflow Flux Residue: NC259 residues can remain on the assembly after reflow and do not require cleaning. Where cleaning is mandated, AIM has worked closely with industry partners to ensure that NC259 residues can be effectively removed with common defluxing agents. Contact AIM for cleaning information.

REFLOW PROFILE

Detailed profile information may be found at http://www.aimsolder.com/reflow-profile-supplements. Contact AIM for additional information.

TEST DATA SUMMARY

NAME	TEST METHOD	RESULTS	
IPC Flux Classification	J-STD-004A	ROL0	
IPC Flux Classification	J-STD-004 Current Rev	ROL1	
NAME	**TEST METHOD**	**TYPICAL RESULTS**	**IMAGE**
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	Before  After 
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	

*All information for reference only. Not to be used as incoming product specifications or for process design. Consult Certificate of Analysis for product specific information.

NAME	TEST METHOD	TYPICAL RESULTS	IMAGE
Oxygen Bomb Halogen Testing	EN14582:2007 SW9056 SW 5050	Halogen Free	
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	PASS	
Viscosity	J-STD-005A 3.5.1 IPC-TM-650 2.4.34 Malcom	130-340 Pa*s	Formula Dependent
Visual	J-STD-004B 3.4.2.5	Gray, Smooth, Creamy	
Slump	J-STD-005A 3.6 IPC-TM-650 2.4.35	PASS	
Solder Ball	J-STD-005A 3.7 IPC-TM-650 2.4.43	PASS	15 Min  4 Hours 
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	
Grain Size of Powder	AIM TM 119PP-09	5 – 15 µm (Type 6) 2-11 µm (Type 7)	

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